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STGFW40H65FB, STGW40H65FB, STGWA40H65FB, STGWT40H65FB

Trench gate field-stop IGBT, HB series 650 V, 40 A high speed

Datasheet - production data

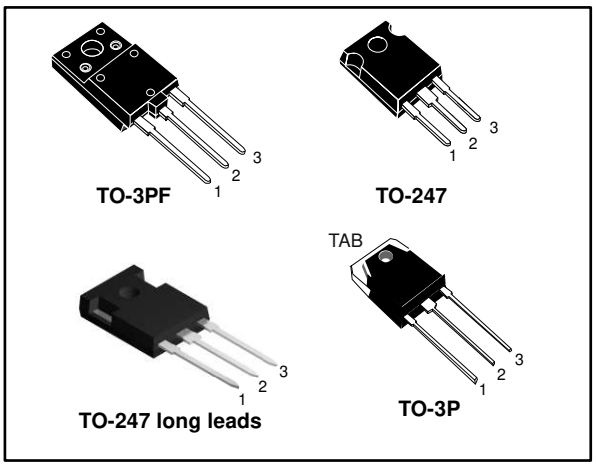
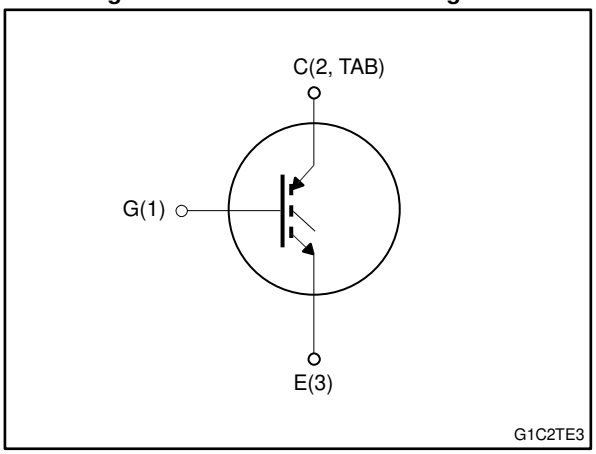


Figure 1: Internal schematic diagram



Features

- Maximum junction temperature: T_J = 175 °C
- High speed switching series
- Minimized tail current
- Very low saturation voltage: $V_{CE(sat)}$ = 1.6 V (typ) @ I_C = 40 A
- Safe paralleling
- Tight parameter distribution
- Low thermal resistance

Applications

- Photovoltaic inverters
- High frequency converters

Description

These devices are IGBTs developed using an advanced proprietary trench gate field-stop structure. These devices are part of the new HB series of IGBTs, which represent an optimum compromise between conduction and switching loss to maximize the efficiency of any frequency converter. Furthermore, the slightly positive $V_{CE(sat)}$ temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packing
STGFW40H65FB	GFW40H65FB	TO-3PF	Tube
STGW40H65FB	GW40H65FB	TO-247	Tube
STGWA40H65FB	GWA40H65FB	TO-247 long leads	Tube
STGWT40H65FB	GWT40H65FB	TO-3P	Tube

Contents

1 Electrical ratings 3
2 Electrical characteristics 4
2.1 Electrical characteristics (curves) 6
3 Test circuits 11
4 Package information 12
4.1 TO-3PF package information 12
4.2 TO-247 package information 14
4.3 TO-247 long leads package information 16
4.4 TO-3P package information 18
5 Revision history 20

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-247, TO-247 long leads, TO-3P	TO-3PF	
V_{CES}	Collector-emitter voltage (V_{GE} = 0 V)	650		V
I_C	Continuous collector current at T_C = 25 °C	80		A
	Continuous collector current at T_C = 100 °C	40		
I_{CP}(1)	Pulsed collector current	160		A
V_{GE}	Gate-emitter voltage	±20		V
P_{TOT}	Total dissipation at T_C = 25 °C	283	62.5	W
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T_C = 25 °C)		3.5	kV
T_{STG}	Storage temperature range	-55 to 150		°C
T_J	Operating junction temperature range	-55 to 175		°C

Notes:

(1)Pulse width is limited by maximum junction temperature.

Table 3: Thermal data

Symbol	Parameter	Value		Unit
		TO-247, TO-247 long leads, TO-3P	TO-3PF	
R_{thJC}	Thermal resistance junction-case	0.53	2.4	°C/W
R_{thJA}	Thermal resistance junction-ambient	50		°C/W

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	V_{GE} = 0 V, I_C = 2 mA	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	V_{GE} = 15 V, I_C = 40 A		1.6	2	V
		V_{GE} = 15 V, I_C = 40 A, T_J = 125 °C		1.7		
		V_{GE} = 15 V, I_C = 40 A, T_J = 175 °C		1.8		
$V_{GE(th)}$	Gate threshold voltage	V_{CE} = V_{GE}, I_C = 1 mA	5	6	7	V
I_{CES}	Collector cut-off current	V_{GE} = 0 V, V_{CE} = 650 V			25	µA
I_{GES}	Gate-emitter leakage current	V_{CE} = 0 V, V_{GE} = ±20 V			±250	nA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	V_{CE}= 25 V, f = 1 MHz, V_{GE} = 0 V	-	5412	-	pF
C_{oes}	Output capacitance		-	198	-	
C_{res}	Reverse transfer capacitance		-	107	-	
Q_g	Total gate charge	V_{CC} = 520 V, I_C = 40 A, V_{GE} = 0 to 15 V (see *Figure 28: "Gate charge test circuit"*)	-	210	-	nC
Q_{ge}	Gate-emitter charge		-	39	-	
Q_{gc}	Gate-collector charge		-	82	-	

Table 6: Switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{CE} = 400 V, I_C = 40 A, V_{GE} = 15 V, R_G = 5 Ω (see *Figure 27: "Test circuit for inductive load switching"*)	-	40	-	ns
t_r	Current rise time		-	13	-	
$(di/dt)_{on}$	Turn-on current slope		-	2413	-	A/µs
$t_{d(off)}$	Turn-off delay time		-	142	-	ns
t_f	Current fall time		-	27	-	
E_{on} (1)	Turn-on switching energy		-	498	-	µJ
E_{off} (2)	Turn-off switching energy		-	363	-	
E_{ts}	Total switching energy		-	861	-	
$t_{d(on)}$	Turn-on delay time	V_{CE} = 400 V, I_C = 40 A, V_{GE} = 15 V, R_G = 5 Ω, T_J = 175 °C (see *Figure 27: "Test circuit for inductive load switching"*)	-	38	-	ns
t_r	Current rise time		-	14	-	
$(di/dt)_{on}$	Turn-on current slope		-	2186	-	A/µs
$t_{d(off)}$	Turn-off delay time		-	141	-	ns
t_f	Current fall time		-	61	-	
E_{on} (1)	Turn-on switching energy		-	1417	-	µJ
E_{off} (2)	Turn-off switching energy		-	764	-	
E_{ts}	Total switching energy		-	2181	-	

Notes:

(1)Including the reverse recovery of the external diode. The diode is the same of the co-packed STGW40H65DFB.

(2)Including the tail of the collector current.

2.1 Electrical characteristics (curves)

Figure 2: Power dissipation vs. case temperature for TO-247, TO-247 long leads and TO-3P

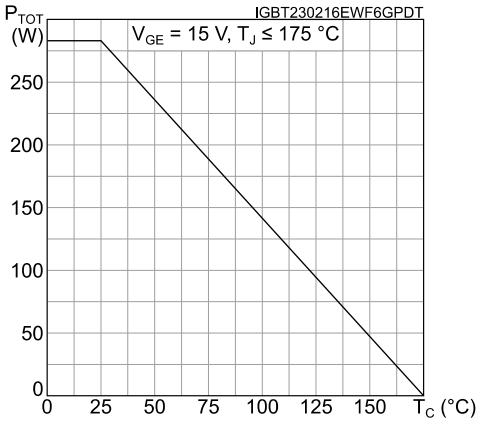


Figure 3: Collector current vs. case temperature for TO-247, TO-247 long leads and TO-3P

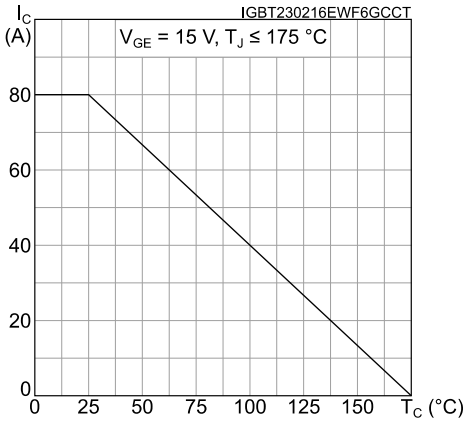


Figure 4: Power dissipation vs. case temperature for TO-3PF

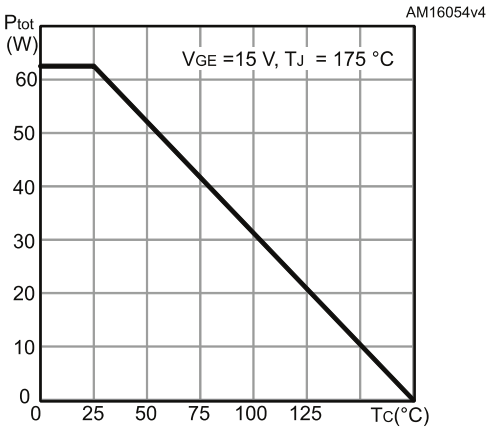


Figure 5: Collector current vs. case temperature for TO-3PF

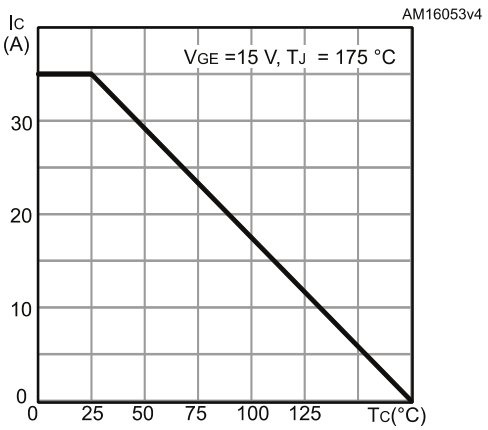


Figure 6: Output characteristics (T_J = 25 °C)

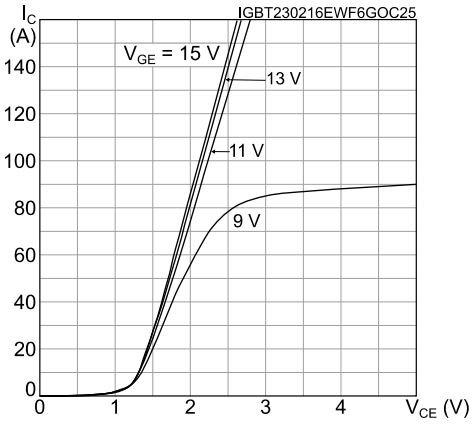


Figure 7: Output characteristics (T_J = 175 °C)

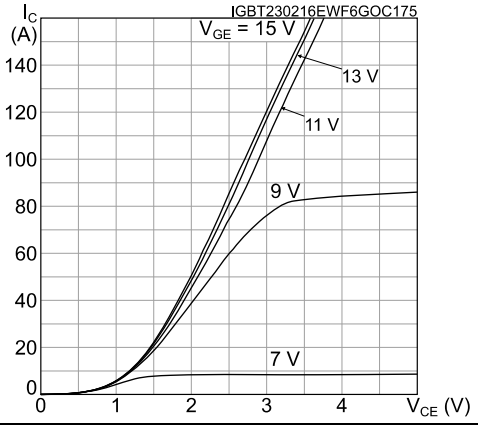


Figure 8: $V_{CE(sat)}$ vs. junction temperature

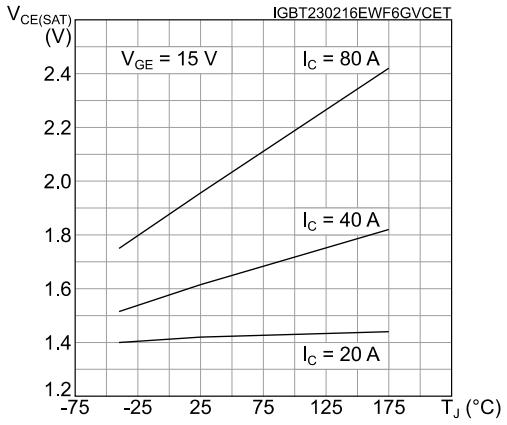


Figure 9: $V_{CE(sat)}$ vs. collector current

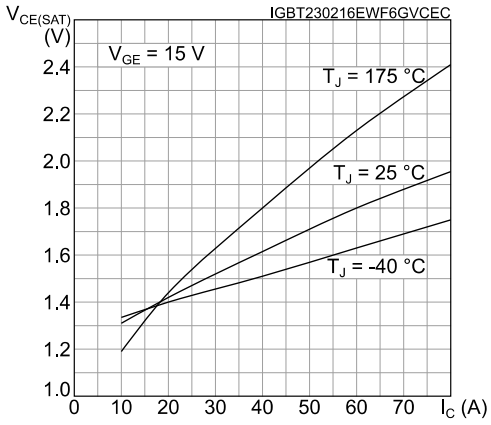


Figure 10: Collector current vs. switching frequency for TO-247,TO-247 long leads and TO-3P

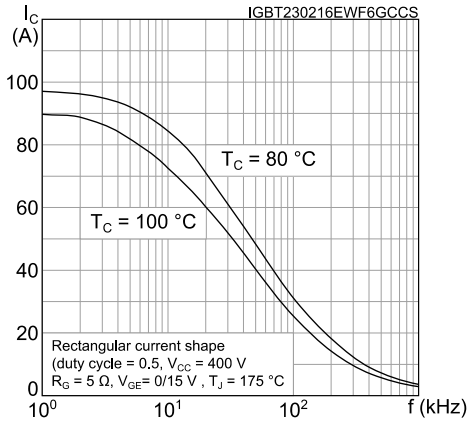


Figure 11: Collector current vs. switching frequency for TO-3PF

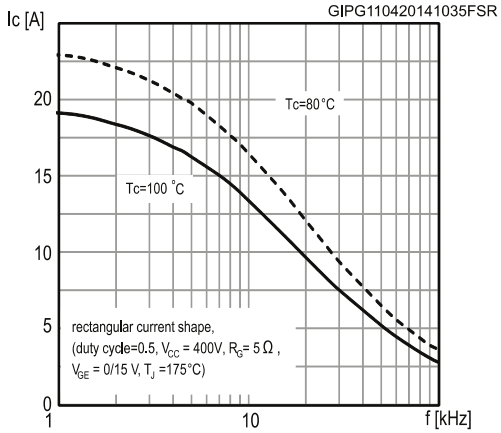


Figure 12: Forward bias safe operating area for TO-247, TO-247 long leads and TO-3P

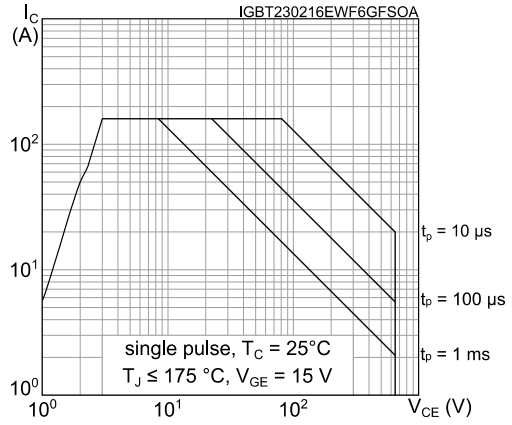


Figure 13: Forward bias safe operating area for TO-3PF

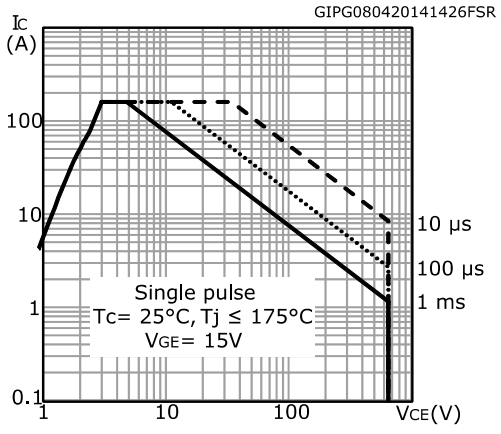


Figure 14: Transfer characteristics

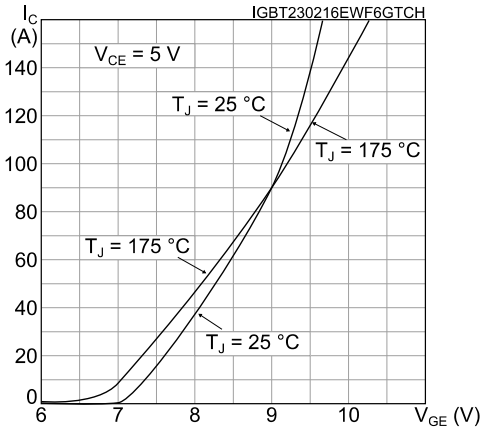


Figure 15: Normalized $V_{GE(th)}$ vs. junction temperature

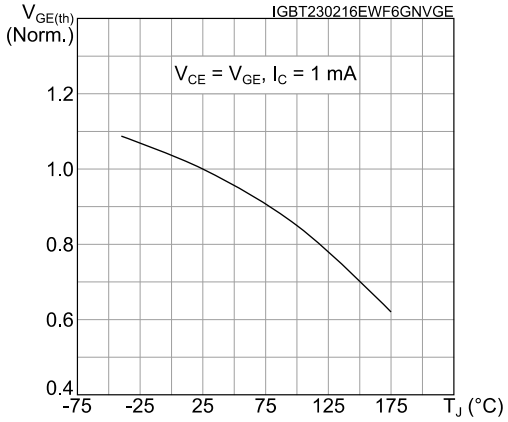


Figure 16: Normalized $V_{(BR)CES}$ vs. junction temperature

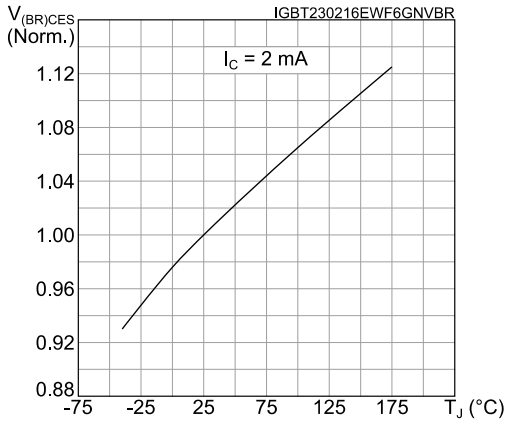


Figure 17: Capacitance variation

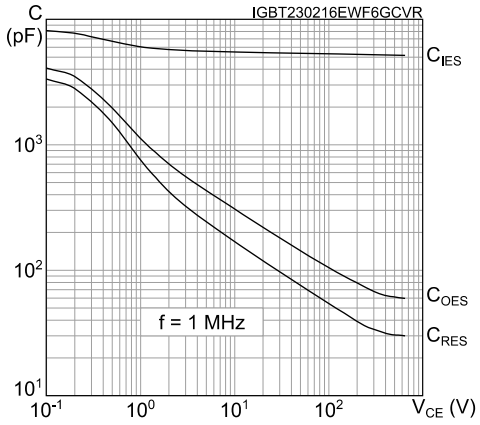


Figure 18: Gate charge vs. gate-emitter voltage

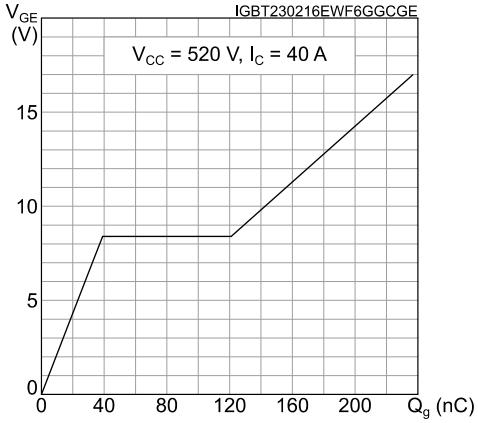


Figure 19: Switching energy vs. collector current

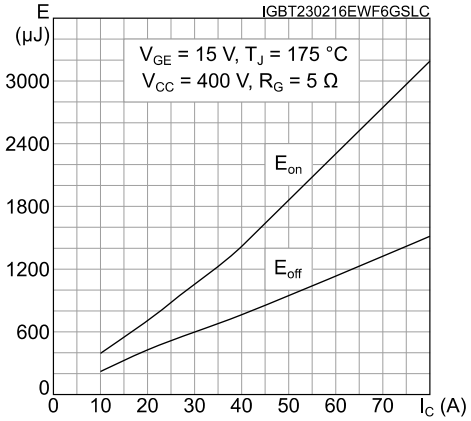


Figure 20: Switching energy vs. gate resistance

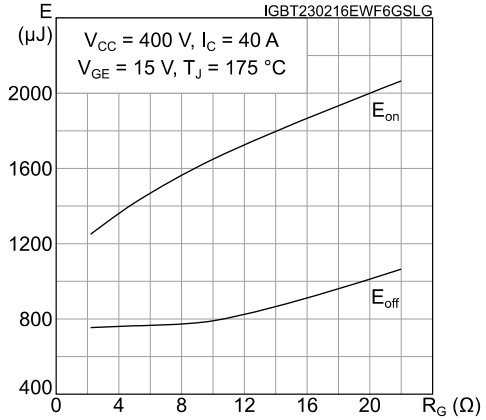


Figure 21: Switching energy vs. temperature

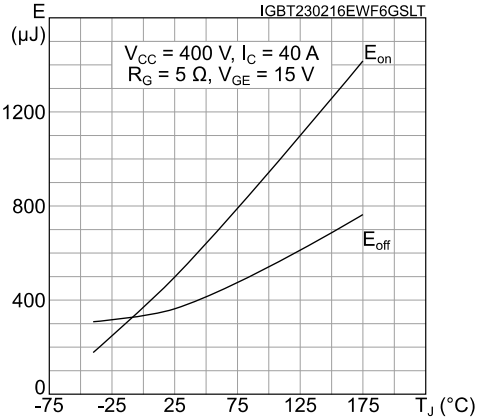


Figure 22: Switching energy vs. collector emitter voltage

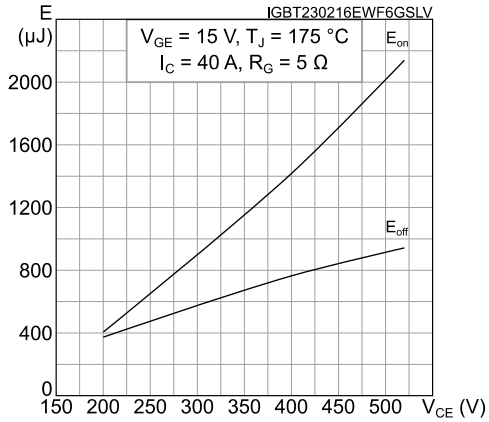


Figure 23: Switching times vs. collector current

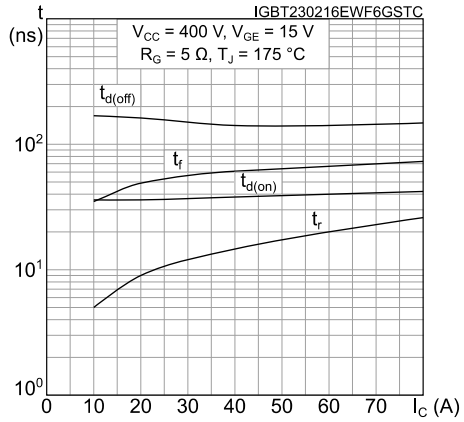


Figure 24: Switching times vs. gate resistance

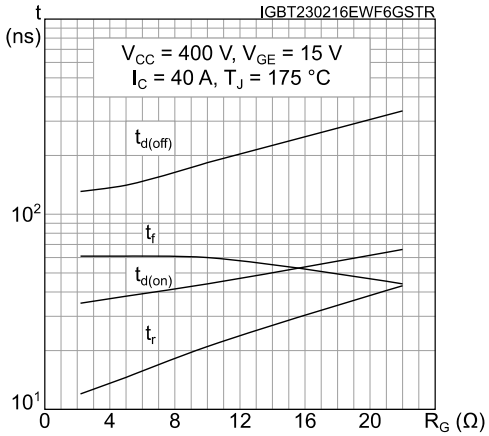


Figure 25: Thermal impedance for TO-247, TO-247 long leads and TO-3P

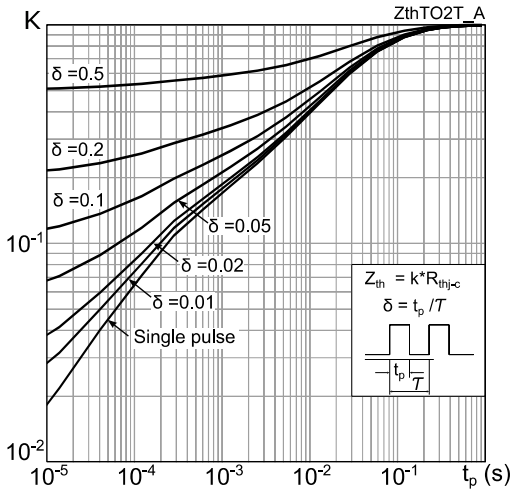
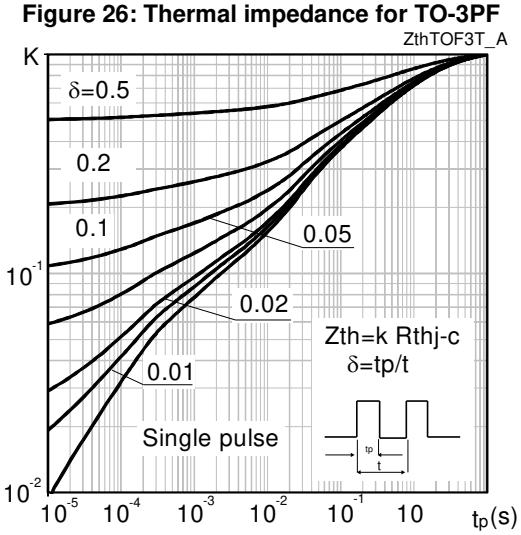


Figure 26: Thermal impedance for TO-3PF



3 Test circuits

Figure 27: Test circuit for inductive load switching

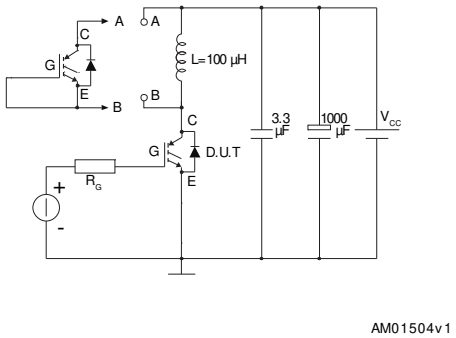


Figure 28: Gate charge test circuit

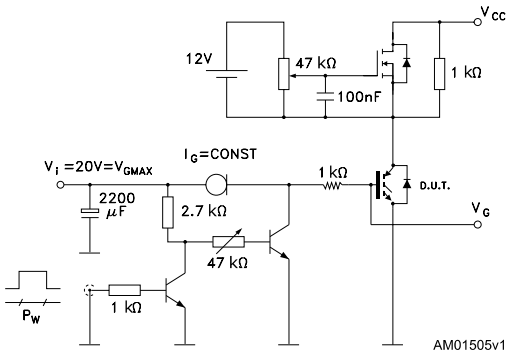
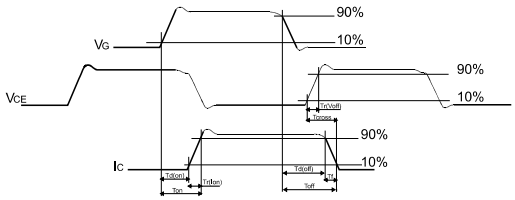


Figure 29: Switching waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: ***www.st.com***. ECOPACK® is an ST trademark.

4.1 TO-3PF package information

Figure 30: TO-3PF package outline

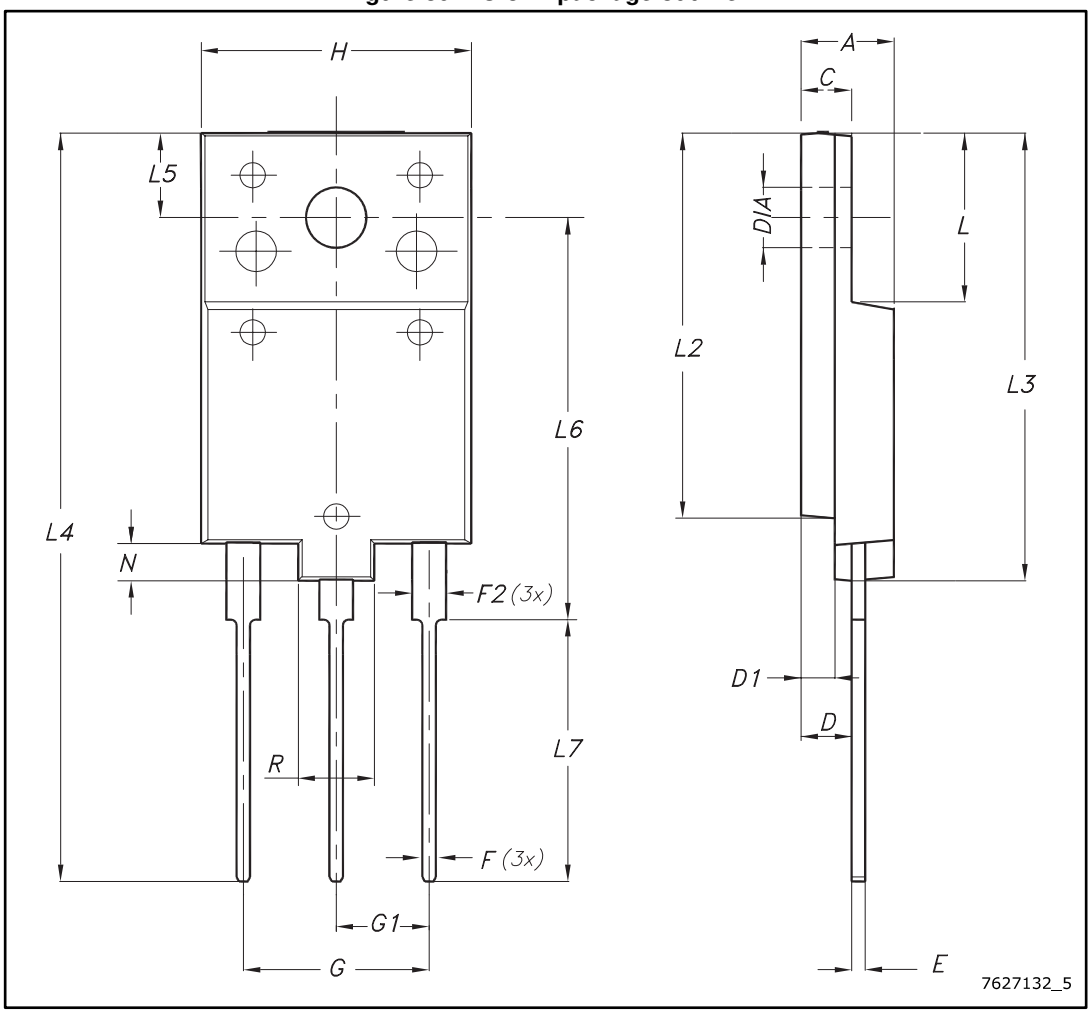


Table 7: TO-3PF mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.10
F	0.65		0.95
F2	1.80		2.20
G	10.30		11.50
G1		5.45	
H	15.30		15.70
L	9.80	10	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.20		44.40
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80

4.2 TO-247 package information

Figure 31: TO-247 package outline

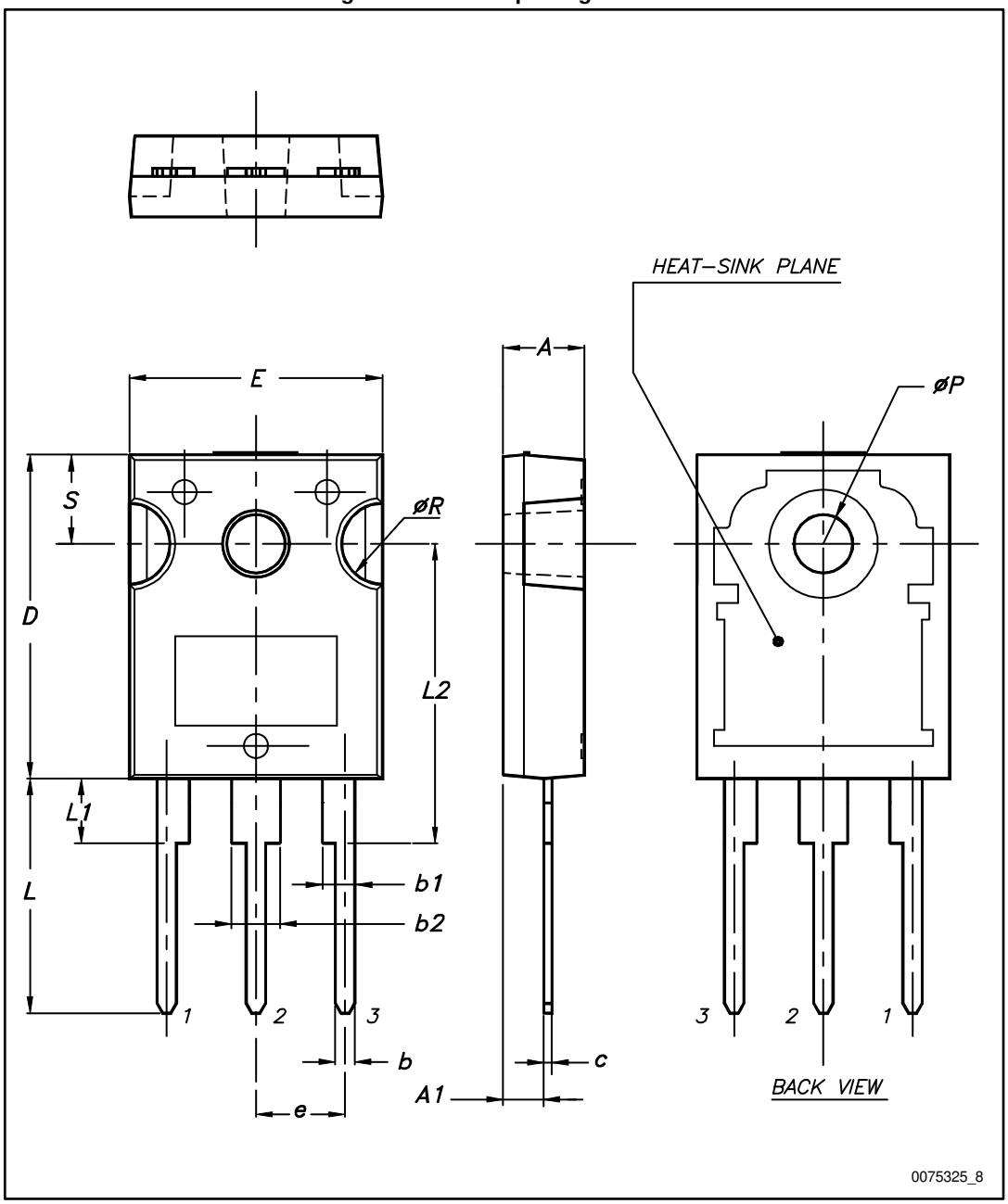


Table 8: TO-247 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

4.3 TO-247 long leads package information

Figure 32: TO-247 long leads package outline

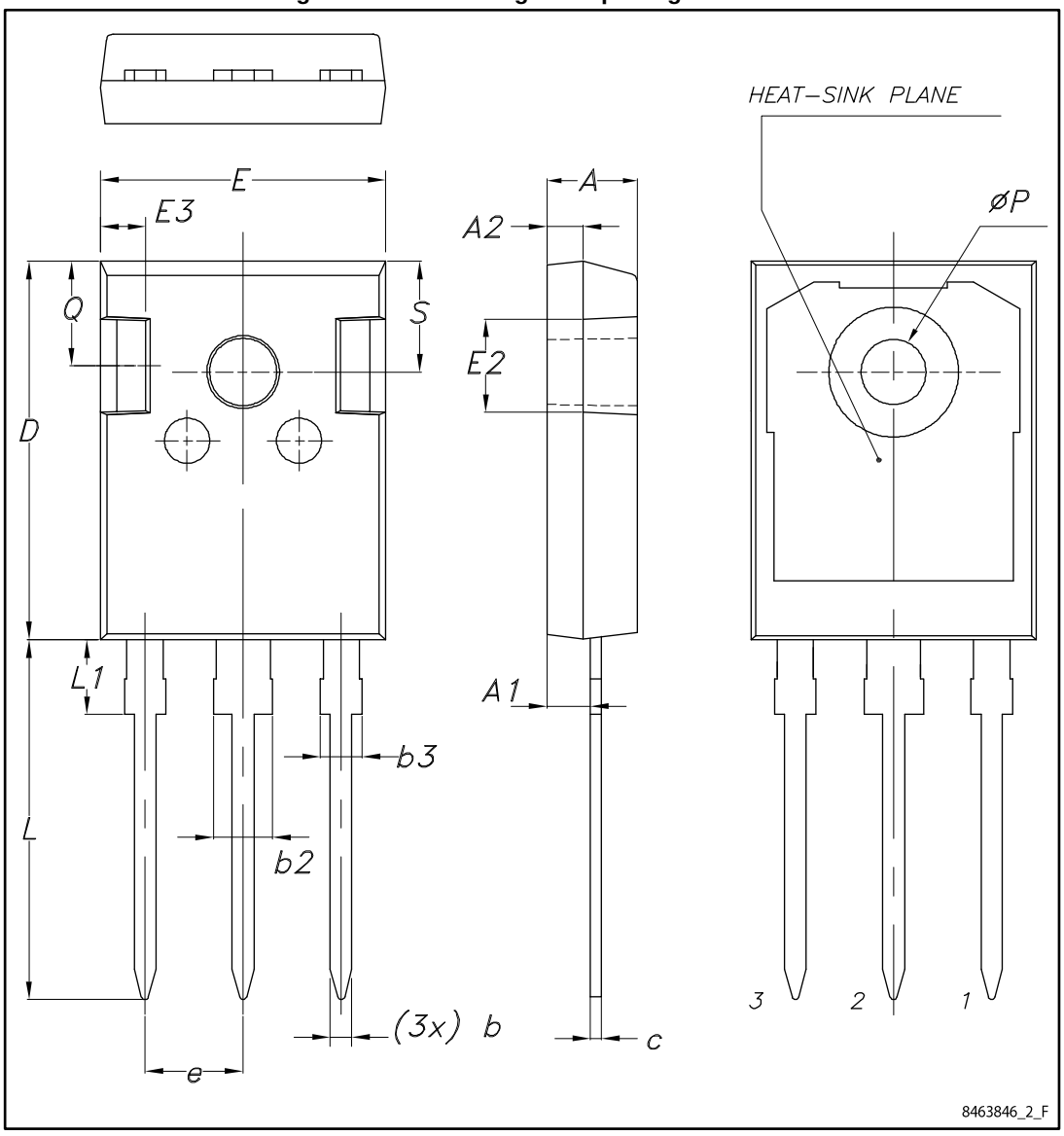


Table 9: TO-247 long leads package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

4.4 TO-3P package information

Figure 33: TO-3P package outline

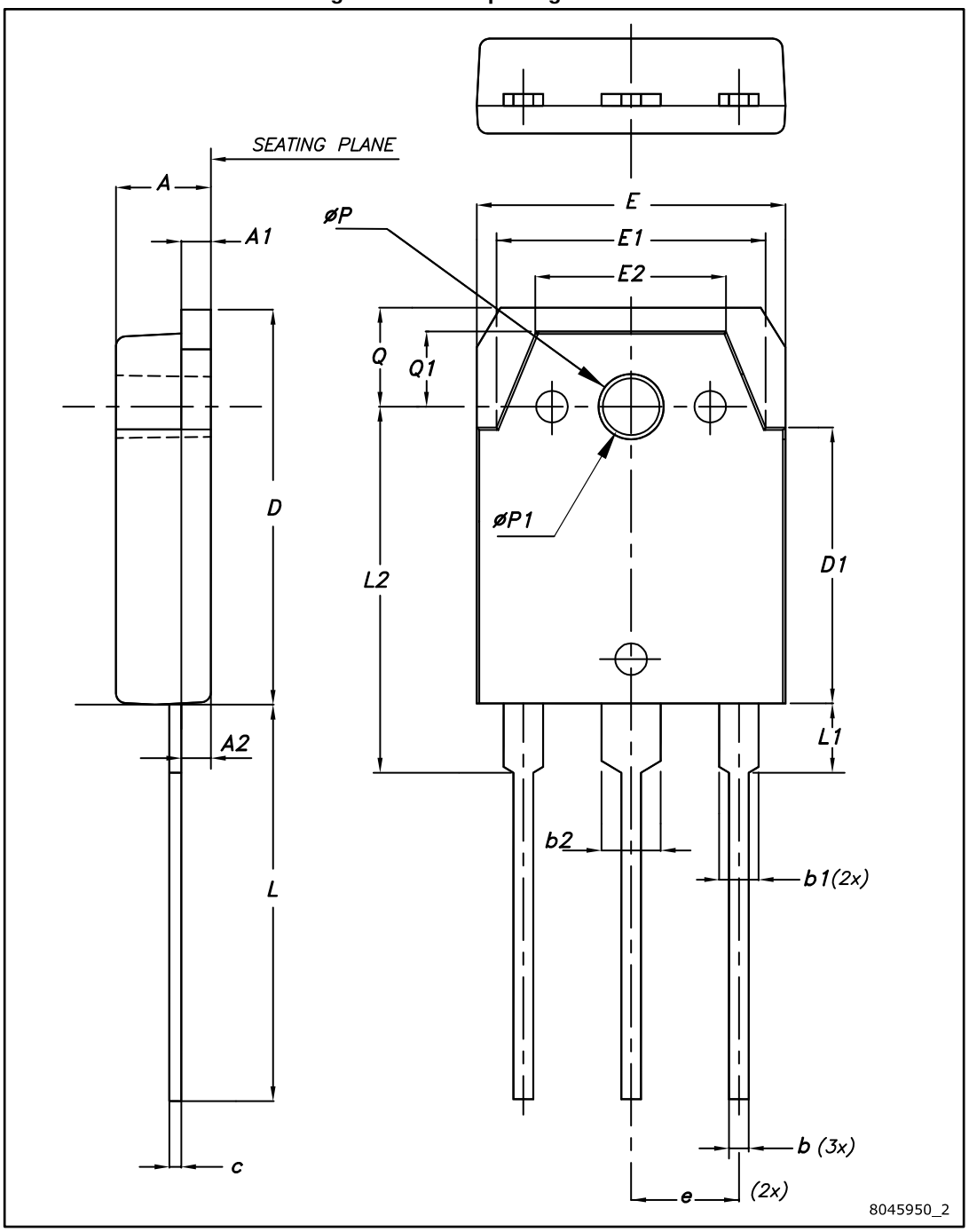


Table 10: TO-3P package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.60	4.80	5.00
A1	1.45	1.50	1.65
A2	1.20	1.40	1.60
b	0.80	1.00	1.20
b1	1.80	2.00	2.20
b2	2.80	3.00	3.20
c	0.55	0.60	0.75
D	19.70	19.90	20.10
D1	13.70	13.90	14.10
E	15.40	15.60	15.80
E1	13.40	13.60	13.80
E2	9.40	9.60	9.90
e	5.15	5.45	5.75
L	19.80	20.00	20.20
L1	3.30	3.50	3.70
L2	18.20	18.40	18.60
ØP	3.30	3.40	3.50
ØP1	3.10	3.20	3.30
Q	4.80	5.00	5.20
Q1	3.60	3.80	4

5 Revision history

Table 11: Document revision history

Date	Revision	Changes
30-Aug-2013	1	Initial release
11-Sep-2013	2	Document status changed from preliminary to production data. Inserted *Section 2.1: Electrical characteristics (curves)*.
28-Feb-2014	3	Updated title and description in cover page.
05-Mar-2014	4	Updated units in *Table 6: Switching characteristics (inductive load)*.
11-Apr-2014	5	Added part number and references for the device in a TO-3PF package.
03-Nov-2016	6	Added device in TO-247 long leads and updated the document accordingly. Updated *Section 2.1: Electrical characteristics (curves)* and *Section 4.3: TO-247 long leads, package information*. Minor text changes.
21-Mar-2017	7	Updated *Table 1: "Device summary"*. Added *Figure 26: "Thermal impedance for TO-3PF"*. Minor text changes

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